C-GRID SHROUDED WAFER

1.0 SCOPE

This specification covers a dual row wafer (header) system on .100 grid. The wafer body has a low profile shroud with a window(s) or open slot(s) to accommodate connector bodies with passive latching ramps. It is designed for P. C. Board mounting and subsequent mating to box contact type connectors

2.0 PRODUCT DESCRIPTION

2.1 Product covered by this specification is for series number 70246, 70247, 71384, 87054, 87256, 87257, 87556, 87834 and 87835

2.2 For dimensions, materials & plating, refer to the appropriate product drawings.

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

The following documents are part of this specification to the extent specified herewith. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence.
In the event of conflict between the requirements of this specification and reference documents, this specification shall take the precedence.

MIL-STD-202 Test Methods for Electrical and Electronic Component Parts.

MIL-STD-1344 Test methods of Electrical Connector

4.0 RATINGS

4.1 Voltage : 250 Volts DC Maximum

4.2 Current : 2.5 Amp DC Min

4.3 Operating Temperature : -55°C to +120°C

5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	**Insulation Resistance**	Measurements taken between adjacent contacts where 500VDC is applied. (MIL-STD-202F, Method 302)	**12000** Megaohms Minimum
2	**Dielectric Strength**	Mated samples subjected to 900 VAC rms for 1 min. between adjacent contacts. (MIL-STD-202F, Method 301)	No breakdown
3	**Current Rating**	Steady state DC voltage source is supplied for 96 hours with a 30 degree C Max. temperature rise over ambient	2.5 amp (D.C.) Maximum

5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
4	**Contact Retention**	Apply axial load at a rate of 0.5 inch/ (12.7mm) minimum up to maximum required load. (MIL-STD-1344A, Method 2007.1)	2 lb / 0.91kgf (Minimum) Initial 0.88 lb / 0.40kgf (Minimum) After resistance to solder heat

5.3 ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	**Resistance to Soldering Heat (Wave Soldering) For Series: 87256, 87257, 87834, 87835, 70246, 70247 87556**	Sample mounted on PCB and subject to wave soldering as per MIL-STD-202G, method 210F, Condition B For series using a) Nylon 4/6 plastic material Temperature : 260 ±5°C for 5sec b) PBT / PET plastic material Temperature : 230 ±5°C for 3sec	No damage in appearance of the connector
6	**Resistance to Soldering Heat (Reflow) For Series: 71384, 87054**	1. Preheat : Increase in temperature < 4°C /sec 2. Soldering : Maximum Reflow temperature < 230°C 3. Cool Down : Cool temperature < 4°C /sec	No damage in appearance of the connector
7	**Solderability**	Solder tail to be dipped in flux as per MIL-STD-202F, method 208	Soldertail should have 95% continuous new solder coating coverage (Apply to non-kinked Soldertail only)

6.0 PACKAGING

Product shall be packaged and protected against damage during handling, transportation and storage.